

# Description

The DGU4520GR is 450 V IGBT with Zener diodes and gate resistors, and achieves an ignition coil drive circuit without an external clamped circuit. The IGBT has low saturation characteristic, and can improve the efficiency of the circuit.

#### **Features**

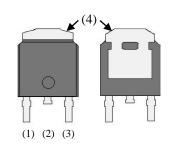
- AEC-Q101 Qualified
- Bare Lead Frame: Pb-free (RoHS Compliant)
- Built-in Zener Diodes
- Built-in Gate Resistors
- Low Saturation Voltage
- V<sub>(BR)CES</sub> ------ 450 V I<sub>C</sub> ------ 20 A
- $V_{CE(SAT)}$  ------ 1.10 V typ. ( $V_{GE} = 4.5 \text{ V}, I_C = 10 \text{ A}$ )

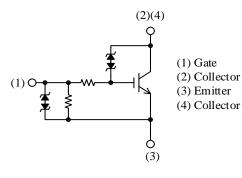
#### Applications

• Ignition Coil Driver Circuits

# **Packages**



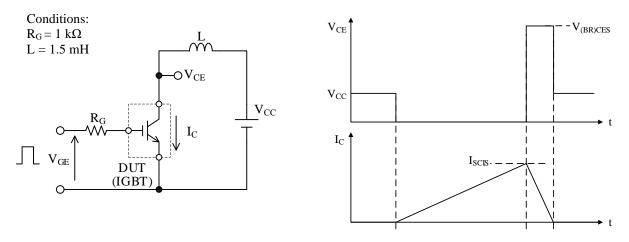




Not to scale

## **Absolute Maximum Ratings**

Unless otherwise specified, $T_A = 25$ °C	C.			
Parameter	Symbol	Conditions	Rating	Unit
Collector-to-Emitter Voltage	V <sub>CE</sub>		V <sub>(BR)CES</sub>	V
Gate-to-Emitter Voltage	V <sub>GE</sub>		±10	V
Continuous Collector Current	I <sub>C</sub>	$T_C = 25 \ ^{\circ}C$	20	А
Power Dissipation	PD	$T_C = 25 \ ^{\circ}C$	172	W
Self-clamped Inductive Switching Energy	E <sub>SCIS</sub>	See Figure 1 and Equation (1).	300	mJ
Self-clamped Inductive Switching Current	I <sub>SCIS</sub>	$V_{CC}^{-} = 14 \text{ V},$ $V_{GE} = 5 \text{ V},$ L = 1.5  mH, $R_{G} = 1  k\Omega$	20	А
Reverse Avalanche Energy	E <sub>AS(R)</sub>	L = 6 mH	2000	mJ
Operating Junction Temperature	TJ		-40 to 175	°C
Storage Temperature	T <sub>STG</sub>		-40 to 175	°C



(a) Test Circuit

(b) Waveform

Figure 1. Self-clamped Inductive Switching Energy Test

$$E_{SCIS} = \frac{1}{2} \times L \times I_{SCIS}^{2} \times \frac{V_{(BR)CES}}{V_{(BR)CES} - V_{CC}}$$

(1)

## **Electrical Characteristics**

Unless otherwise specified, $T_A = 25 \ ^{\circ}C$ .							
Parameter	Symbol	Conditions		Min.	Тур.	Max.	Unit
Collector-to-Emitter Breakdown Voltage	V <sub>(BR)CES</sub>	$I_C = 2 \text{ mA}, V$	$V_{\rm GE} = 0 \ {\rm V}$	425	450	475	v
Gate-to-Emitter Breakdown Voltage	V <sub>(BR)GES</sub>	$I_{G} = \pm 1 \text{ mA}, V_{CE} = 0 \text{ V}$		±10.0	±11.5	±13.0	V
Collector-to-Emitter Leakage Current	I <sub>CES</sub>	$V_{CE} = 350 \text{ V}$	, $V_{GE} = 0 V$			100	μΑ
Emitter-to-Collector Leakage Current	I <sub>ECS</sub>	$V_{EC} = 24 V$				1.0	mA
Gate-to-Emitter Leakage Current	I <sub>GES</sub>	$V_{GE} = \pm 5 \ V$		±89	±106	±132	μA
Gate Threshold Voltage	V <sub>GE(TH)</sub>	$V_{CE} = 10 V$ ,	$I_C = 1 \text{ mA}$	1.40	1.75	2.10	V
Collector-to-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	$T_J = 25 \ ^\circ C$	$V_{GE} = 3.5 \text{ V},$ $I_C = 10 \text{ A}$		1.16	1.39	V
			$V_{GE} = 4.5 V, I_C = 10 A V_{GE} = 4.5 V, $	_	1.10	1.32	V
			$V_{GE} = 4.5 \text{ V},$ $I_C = 15 \text{ A}$	_	1.25	1.50	V
			$V_{GE} = 4.5 \text{ V},$ $I_C = 20 \text{ A}$		1.39	1.67	V
		$T_J = 150 \ ^\circ C$	$V_{GE} = 3.5 V,$ $I_C = 10 A$		1.15	1.50	V
			$V_{GE} = 4.5 \text{ V},$ $I_C = 10 \text{ A}$	_	1.08	1.40	V
			$I_{C} = 10 \text{ A}$ $V_{GE} = 4.5 \text{ V},$ $I_{C} = 15 \text{ A}$	_	1.31	1.77	V
			$V_{GE} = 4.5 \text{ V},$ $I_C = 20 \text{ A}$	_	1.58	2.13	V
Input Capacitance	Cies	$V_{CE} = 10 \text{ V},$ $V_{GE} = 0 \text{ V},$ f = 1.0  MHz			1900		pF
Output Capacitance	C <sub>oes</sub>			_	460		pF
Reverse Transfer Capacitance	C <sub>res</sub>				160		pF
Turn-on Delay Time	t <sub>d(ON)</sub>	Resistive load,			1.3		μs
Rise Time	tr	see Figure 3			3.8		μs
Turn-off Delay Time	t <sub>d(OFF)</sub>	Inductive load,			13.5		μs
Fall Time	t <sub>f</sub>	see Figure 4			2.7		μs
Internal Series Gate Resistor <sup>(1)</sup>	R <sub>G(INT)</sub>				70		Ω
Internal Gate-to-Emitter Resistor <sup>(1)</sup>	R <sub>GE(INT)</sub>	$T_J = -40$ to 175 °C		37.6	47.0	61.1 <sup>(2)</sup>	kΩ

Unless otherwise specified,  $T_{A} = 25 \ ^{\circ}C$ 

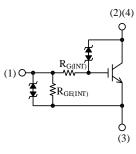


Figure 2. Internal Gate Resistor

<sup>(1)</sup> See Figure 2

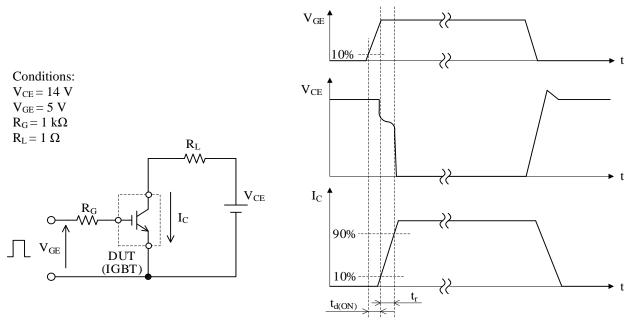
<sup>(2)</sup> Guaranteed by design.

## **Thermal Characteristics**

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Thermal Resistance (Junction-to-Case)	$R_{ ext{ hetaJC}}$			_	0.87	°C/W

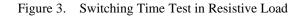
# **Mechanical Characteristics**

Parameter	Conditions	Min.	Тур.	Max.	Unit
Package Weight		_	0.32	_	g



(a) Test Circuit

(b) Waveform



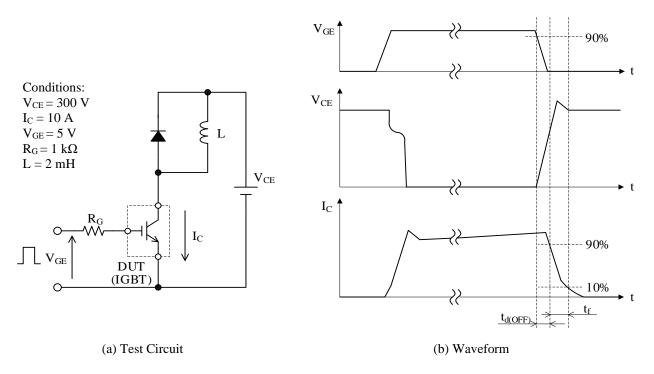
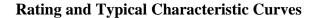
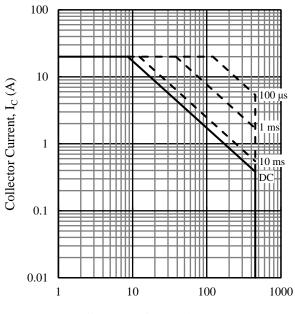


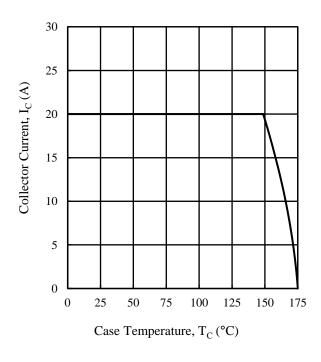
Figure 4. Switching Time Test in Inductive Load

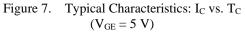




Collector-Emitter Voltage, V<sub>CE</sub> (V)







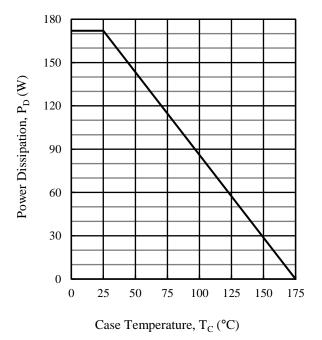


Figure 6. Typical Characteristics: PD vs. TC

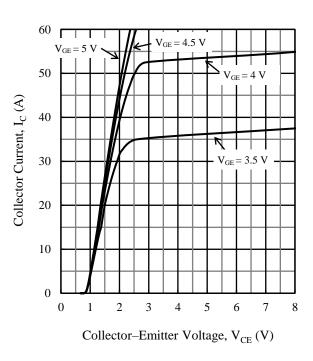


Figure 8. Typical Characteristics:  $I_C \mbox{ vs. } V_{CE}$   $(T_J = -40 \ ^\circ C)$ 

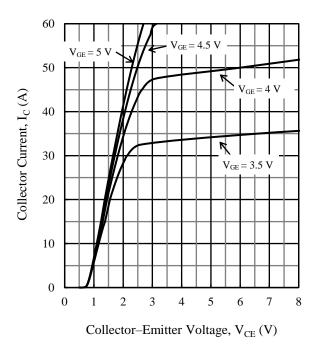


Figure 9. Typical Characteristics:  $I_C$  vs.  $V_{CE}$ ( $T_J = 25 \ ^\circ C$ )

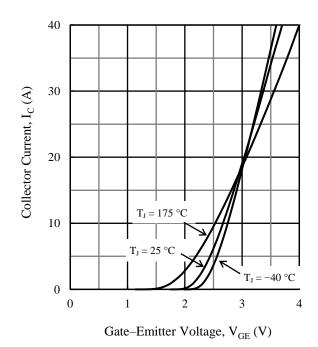


Figure 11. Typical Characteristics:  $I_C$  vs.  $V_{GE}$ ( $V_{CE} = 5$  V)

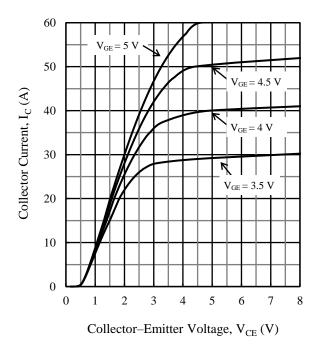


Figure 10. Typical Characteristics:  $I_C$  vs.  $V_{CE}$ ( $T_J = 175 \ ^\circ C$ )

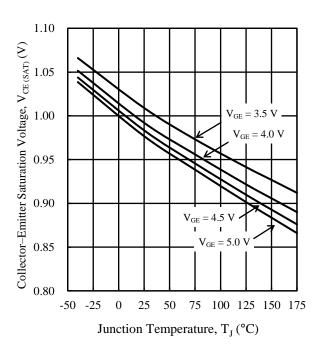


Figure 12. Typical Characteristics:  $V_{CE(SAT)}$  vs.  $T_J$  (I<sub>C</sub> = 6 A)

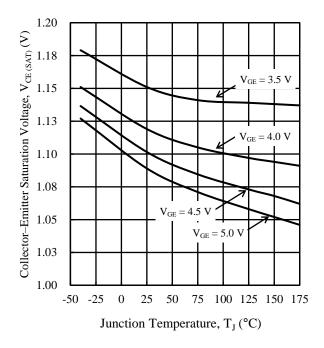


Figure 13. Typical Characteristics:  $V_{CE(SAT)}$  vs.  $T_J$  (I<sub>C</sub> = 10 A)

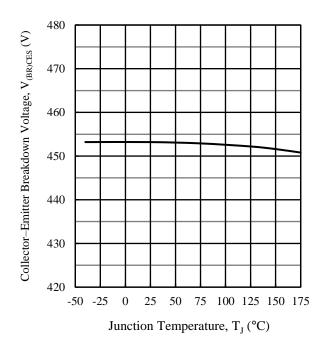


Figure 15. Typical Characteristics:  $V_{(BR)CES}$  vs.  $T_J$ ( $V_{GE} = 0$  V,  $I_C = 2$  mA)

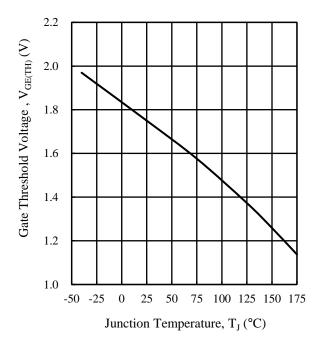


Figure 14. Typical Characteristics:  $V_{GE(TH)}$  vs.  $T_J$  ( $V_{CE} = 10$  V,  $I_C = 1$  mA)

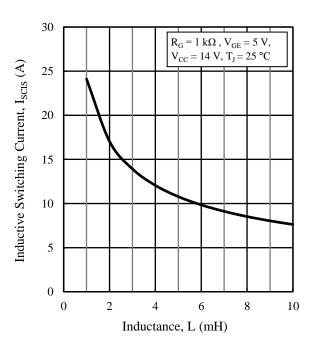
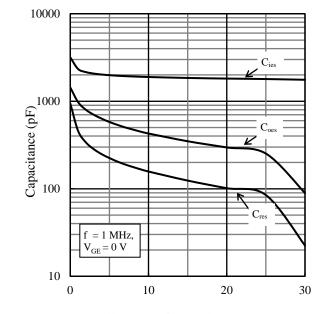


Figure 16. Typical Characteristics: I<sub>SCIS</sub> vs. L



Collector–Emitter Voltage,  $V_{CE}(V)$ 

Figure 17. Typical Characteristics: Capacitance vs.  $V_{CE}$ 

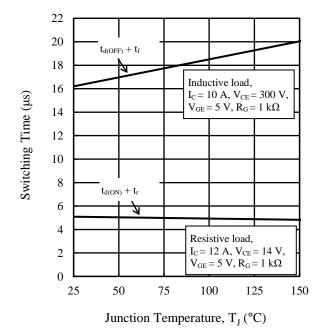


Figure 19. Typical Characteristics: Switching Time vs. T<sub>J</sub>

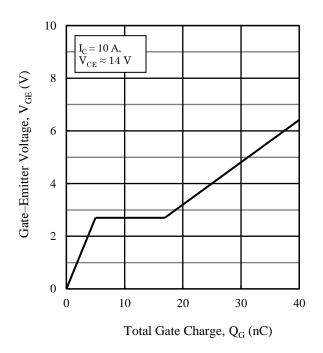


Figure 18. Typical Characteristics: V<sub>GE</sub> vs. Q<sub>G</sub>

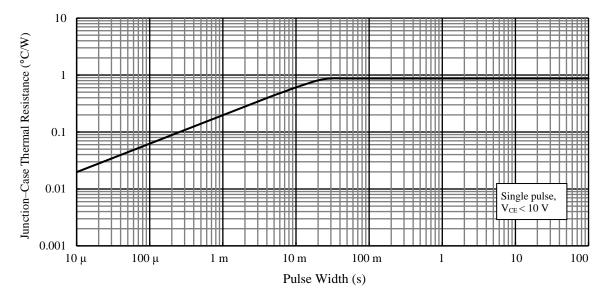
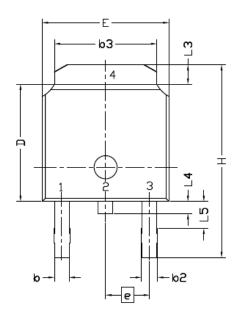
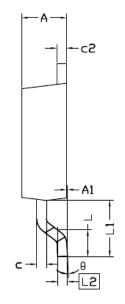


Figure 20. Typical Transient Thermal Resistance Characteristics

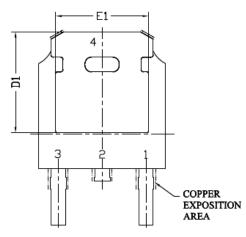
### **Physical Dimensions**

#### • TO252-2L Package





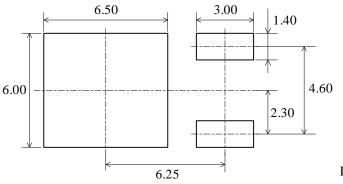
SYMBOL	DIMENS:		REQMIS
STREEL	MIN	NDM	MAX
Ŀ	6.40	6.60	6.731
L	1,40	1.52	1.77
L1	2	.743 R	ĒF
L2	0.	508 BS	С
L3	0,89		1.27
L4	0.64		1.01
L5			
D	6.00	6.10	6.223
Н	9,40	10.00	10.40
0	0.64	0,76	0,88
50	0,77	0,84	1.14
b3	5,21	5.34	5,46
e	2.	286 BS	С
Α	5'50	2.30	2.38
A1	0		0.127
L	0,46	0.50	0.60
c2	0,46	0,50	0.58
D1	5.21		
E1	4,40		
θ	0°		10°



#### NOTES:

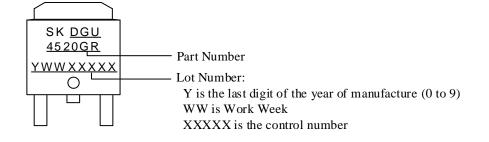
- Dimensions in millimeters
- All the dimensions exclude mold flashes.
- Bare lead frame: Pb-free (RoHS compliant)
- Moisture Sensitivity Level 1 (MSL 1)
- When soldering the products, it is required to minimize the working time within the following limits: Reflow
  - Preheat: 150 °C to 200 °C / 60 s to 120 s
  - Solder heating: 255 °C / 30 s, 3 times (260 °C peak) Soldering iron: 350 °C / 3.5 s, 1 time

#### • TO252-2L Land Pattern Example



Dimensions in millimeters

# **Marking Diagram**



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